

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Kripesh, et al.) Group Art Unit
App. No. : 10/078,243) 2815
Filed : February 14, 2002)
For : PROCESS OF FORMING METAL)
SURFACES COMPATIBLE WITH)
A WIRE BONDING AND)
SEMICONDUCTOR)
INTEGRATED CIRCUITS)
MANUFACTURED BY THE)
PROCESS)
Examiner : Unknown)

INFORMATION DISCLOSURE STATEMENT

United States Patent and Trademark Office
P.O. Box 2327
Arlington, VA 22202

Dear Sir:

Enclosed is form PTO-1449 listing references that are also enclosed. This Information Disclosure Statement is being filed before the receipt of a first Office Action on the merits, and presumably no fee is required in accordance with 37 C.F.R. § 1.97(b)(3).

Along with the new reference cited in this PTO-1499, Applicant submits application SG 060018 A1 that was cited in a PTO-1449 filed on February 14, 2002. At the time, Applicant's attorney did not have the document and only made cite to it.

If a first Office Action on the merits was mailed before the mailing date of this Statement,

Appl. No. : 10/078,2
Filed : February 14, 2002

the Commissioner is authorized to charge the fee set forth in 37 C.F.R. § 1.17(p) to
Deposit Account No. 11-1410.

Respectfully submitted,

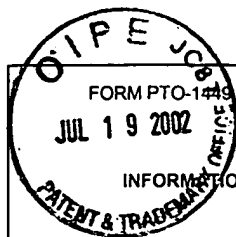
KNOBBE, MARTENS, OLSON & BEAR, LLP

Dated: 7/15/02

By: 

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FORM PTO-1449

JUL 19 2002

INFORMATION DISCLOSURE STATEMENT
BY APPLICANT

(USE SEVERAL SHEETS IF NECESSARY)

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
ALLEN4.001AUSAPPLICATION NO.
10/078,243APPLICANT
Kripesh, et al.FILING DATE
February 14, 2002GROUP
2815

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)

FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO

EXAMINER INITIAL	OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)
	George G. Harman, "Wire bonding in Microelectronics Materials, Processes, Reliability, and Yield", 2 nd Edition, Table of contents and Chapter 1.

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EXAMINER	DATE CONSIDERED
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*EXAMINER: INITIAL IF CITATION CONSIDERED, WHETHER OR NOT CITATION IS IN CONFORMANCE WITH MPEP 609; DRAW LINE THROUGH CITATION IF NOT IN CONFORMANCE AND NOT CONSIDERED. INCLUDE COPY OF THIS FORM WITH NEXT COMMUNICATION TO APPLICANT.